WHAT IS CLAIMED IS:

1. A carrier for used in manufacturing a semiconductor encapsulant package, which comprises:

at least one receiving part for used in receiving the semiconductor encapsulant package; and

a plurality of positioning pins protruding upwards from an edge of the receiving part for used in positioning the semiconductor encapsulant package on the carrier; wherein an obtuse angle θ is between the positioning pin and the receiving part.

2. The carrier as claimed in Claim 1, wherein the semiconductor encapsulant package exerts a friction force and a gliding force when contacting with the positioning pins, and the obtuse angle θ between the positioning pin and the receiving part allows the friction force larger than the gliding force.

3. The carrier as claimed in Claim 1, wherein the obtuse angle θ between the positioning pin and the receiving part is larger than 9 1 ° .

4. The carrier as claimed in any of Claims 1, 2 and 3, wherein the obtuse angle θ between the positioning pin and the receiving part is from 91° to 110°.

5. The carrier as claimed in any of Claims 1, 2 and 3, wherein the obtuse angle θ between the positioning pin and the receiving part is from 91° to 96°.

6. The carrier as claimed in Claim 1, wherein a first plane of the positioning pin facing the semiconductor encapsulant package is slant and a second plane of the positioning pin opposite the semiconductor encapsulant package is vertical, and wherein the second plane of the positioning pin is

at an angle of about 90° to the receiving part.

7. The carrier as claimed in Claim 1, wherein a first plane of the positioning pins facing the semiconductor encapsulant package is slant and a second plane of the positioning pin opposite the semiconductor encapsulant package is also slant; wherein the second plane is substantially parallel to the first plane.

8. The carrier as claimed in Claim 1, wherein the positioning pins and the receiving parts are integrally formed.